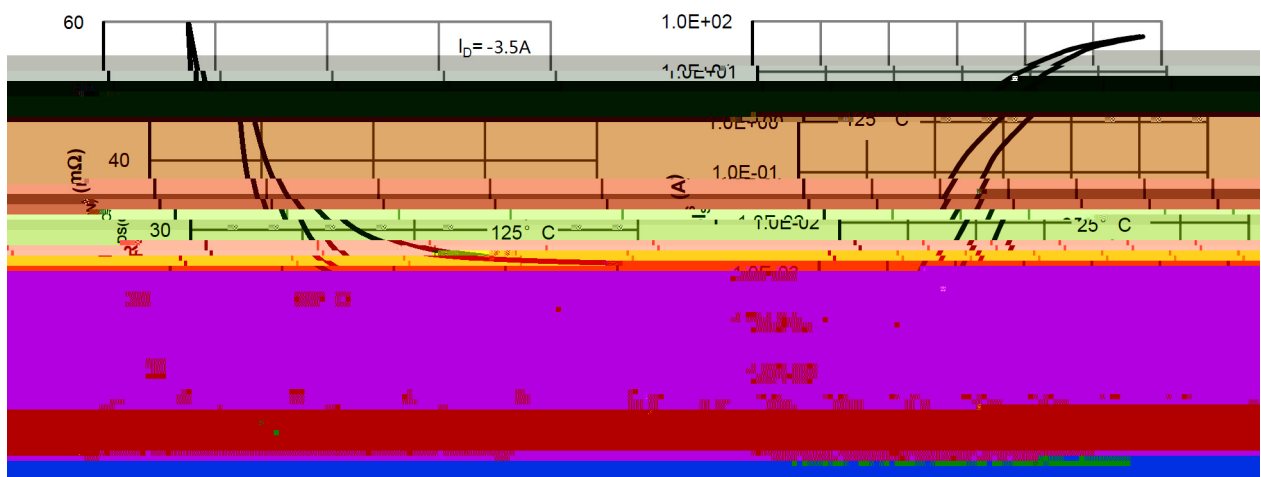
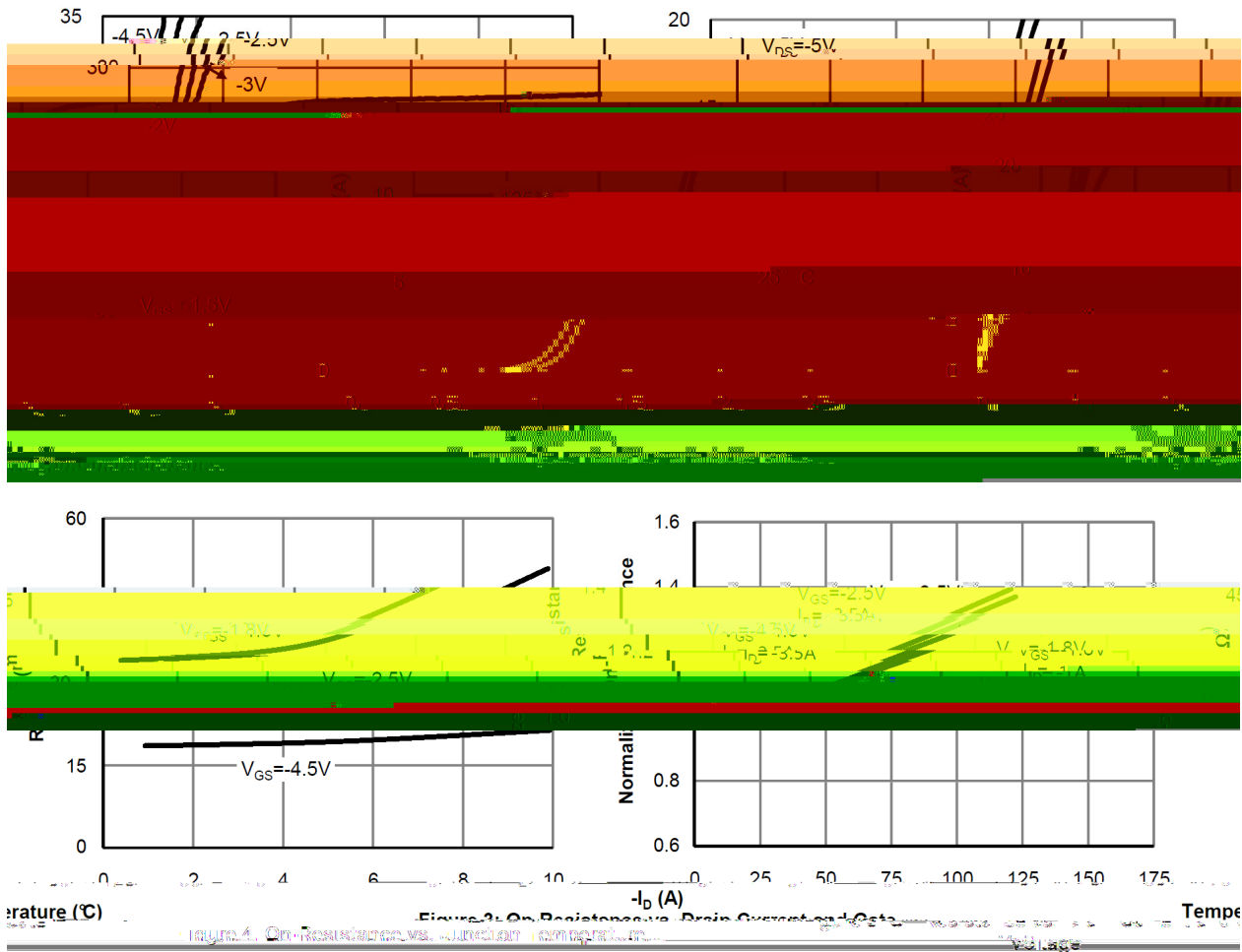


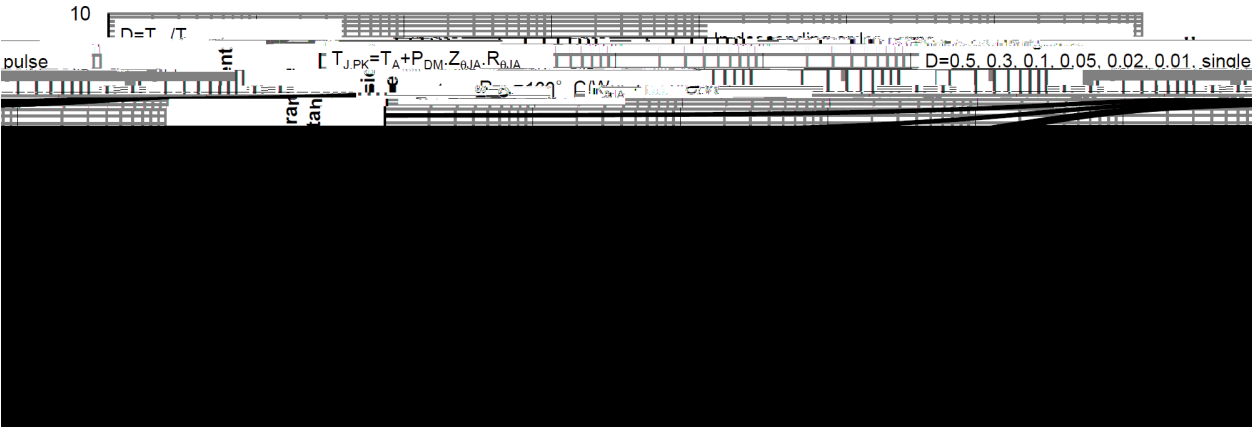
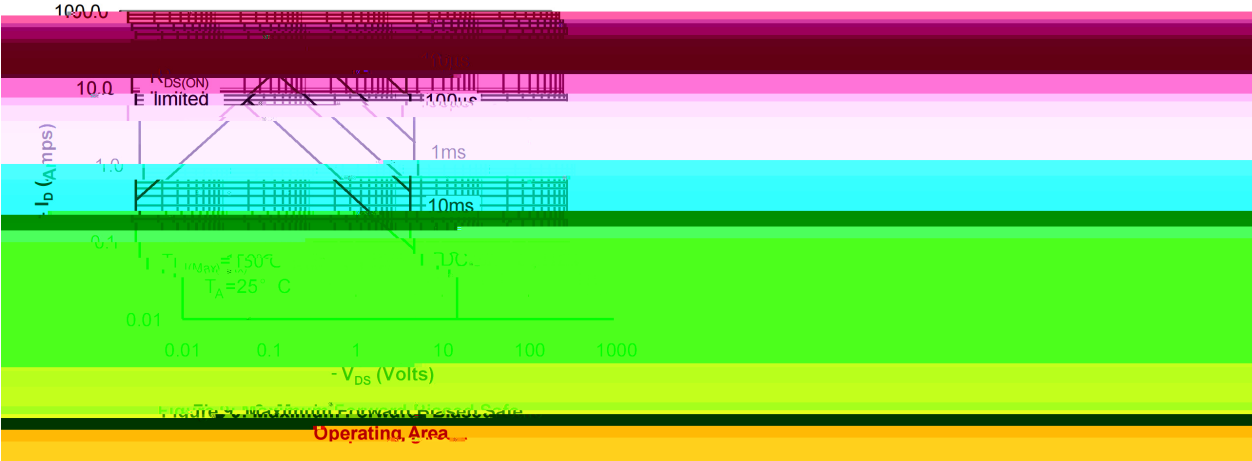
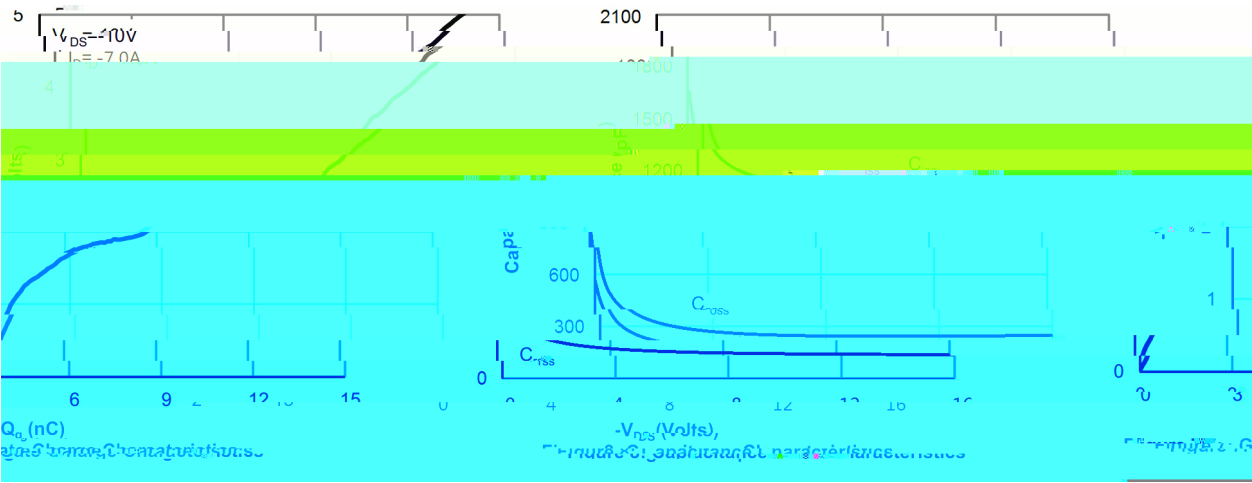
/ Electrical Characteristics(Ta=25)

Parameter	Symbol	Test Conditions	Min	Typ	Max	Unit
Total Gate Charge	Q_g	$V_{GS}=-4.5V, \quad V_{DS}=-10V,$ $I_D=-7.0A$		10.4		nC
Gate Source Charge	Q_{gs}			1.1		
Gate Drain Charge	Q_{gd}			2.1		
Turn-On Delay Time	$t_{d(on)}$	$V_{GS}=-4.5V \quad I_D=-7.0A$ $V_{DS}=-10V \quad R_{GEN}=3$		11.4		ns
Turn-On Rise Time	t_r			49.3		
Turn-Off Delay Time	$t_{d(off)}$			55.9		
Turn-Off Fall Time	t_f			31.6		

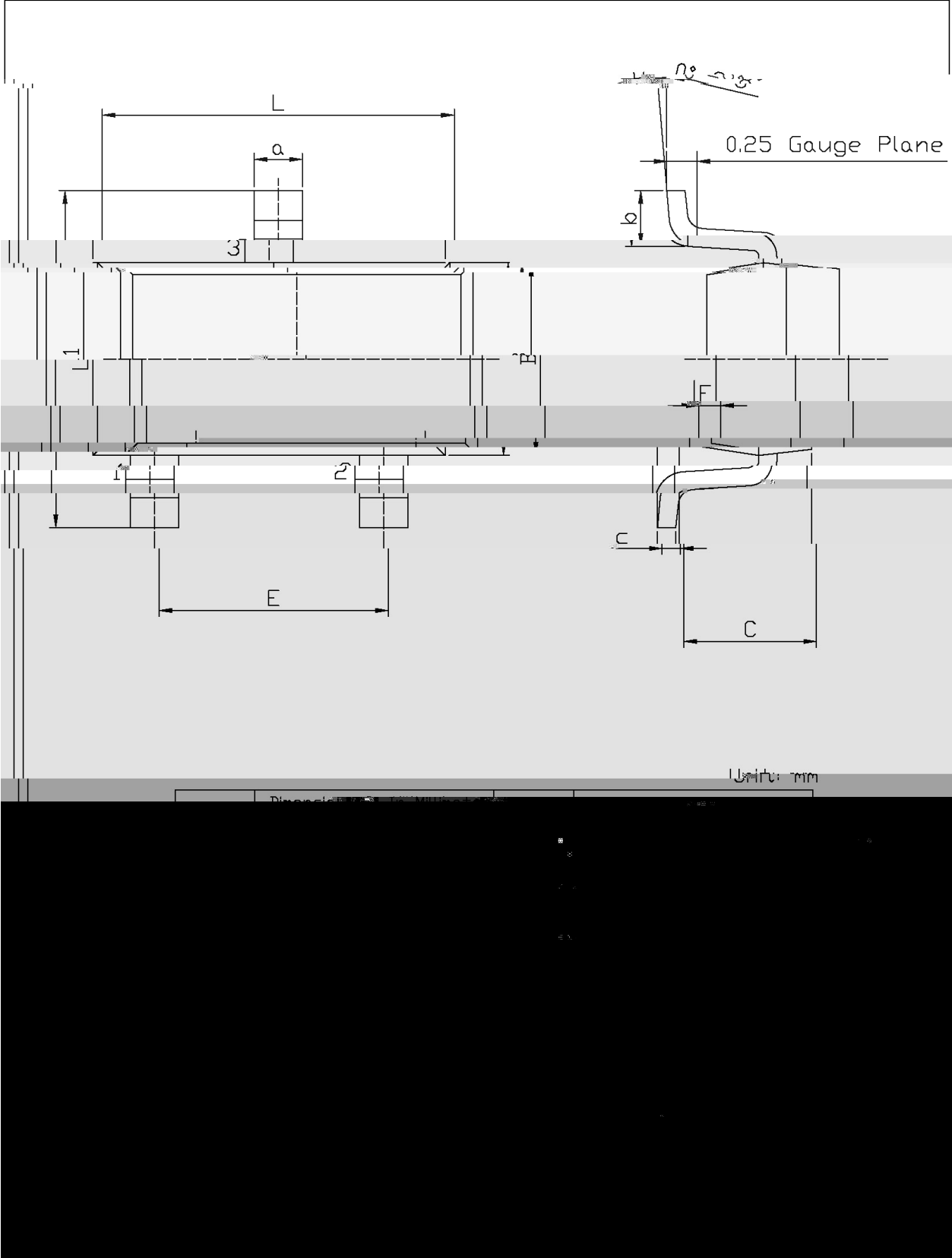
/ Electrical Characteristic Curve



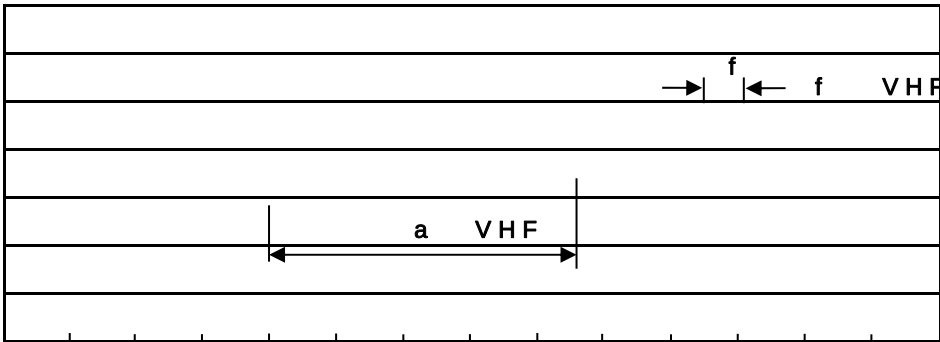
/ Electrical Characteristic Curve



/ Package Dimensions



() / Temperature Profile for IR Reflow Soldering(Pb-Free)



- Note:
- 1

150 180

60 90sec;

2

245±5

5±0.5sec;
- 3

2 10 /sec.
- 1.Preheating:150~180 , Time:60~90sec.

2.Peak Temp.:245±5 , Duration:5±0.5sec.

3. Cooling Speed: 2~10 /sec.

/ Resistance to Soldering Heat Test Conditions

260±5 10±1 sec. Temp.:260±5 Time:10±1 sec

/ Packaging SPEC.

/ REEL

Package Type 7>û ~ E	Units ;>û H					Dimension ;>û p . (unit Åmm³)		
	Units/Reel /-	Reels/Inner Box -- /-	Units/Inner Box /-	Inner Boxes/Outer Box - /1ç	Units/Outer Box /1ç	Reel	Inner Box	Outer Boxç
SOT23-3	3,000	10	30,000	4	120,000	7 s ×8	210×205×205	445×435×230

/ Notices

All information provided in this document is subject to legal disclaimers.